

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
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EPAS ID: PAT5819418

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PING-HUNG SHIH	07/18/2019
WEI-CHIEH SUN	07/18/2019
PENG-CHE TAI	07/18/2019
CHIA-HENG CHEN	07/18/2019
JHIH-CI CHEN	07/18/2019
MENG-TING HSIEH	07/18/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	AU OPTRONICS CORPORATION
<b>Street Address:</b>	NO. 1, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK,
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16679236
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)391-4699
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<b>ATTORNEY DOCKET NUMBER:</b>	087196-US-PA
<b>NAME OF SUBMITTER:</b>	BELINDA LEE
<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	11/14/2019
<b>Total Attachments: 4</b> source=087196-dcl-asm#page1.tif	

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**DISPLAY PANEL, DRIVER CIRCUIT, AND MANUFACTURING METHOD  
OF DISPLAY PANEL**

As a below named inventor (hereinafter designated as the undersigned), I hereby  
declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

\_\_\_\_\_ Filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in  
the application.

The undersigned hereby acknowledge that any willful false statement made in this  
declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more  
than five (5) years, or both.

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**DECLARATION AND ASSIGNMENT**  
**FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

**WHEREAS,** 1. Au Optronics Corporation  
of No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: 石秉弘 Date: 2019.7.18

Legal Name of Sole or First Inventor: **Ping-Hung Shih**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: 孫偉傑 Date: 2019.7.18

Legal Name of Additional Joint Inventor, if any: **Wei-Chieh Sun**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: 戴鵬哲 Date: 2019.7.18

Legal Name of Additional Joint Inventor, if any: **Peng-Che Tai**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: 陳嘉亨 Date: 2019.7.18

Legal Name of Additional Joint Inventor, if any: **Chia-Heng Chen**

Residence: Kaohsiung City, Taiwan

Mailing Address: c/o No. 1, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

Signature: 陳以錫 Date: 2019.7.18

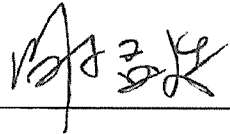
Legal Name of Additional Joint Inventor, if any: **Jih-Ci Chen**

Residence: Hsinchu, Taiwan

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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature:  Date: 2019/7/18

Legal Name of Additional Joint Inventor, if any: **Meng-Ting Hsieh**

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